

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/829,647

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND
PACKAGING OF FLIP CHIP
CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6967

Examiner: P. Perkins

Group Art Unit: 2822

Attorney Docket No.: 2269-4974.1US
(00-0693.01/US)

OK TO ENTER: /PEP/

VIA ELECTRONIC FILING
February 19, 2008

RESPONSE TO FINAL OFFICE ACTION

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following remarks are filed in response to the Examiner's remarks in the Final Office Action mailed December 17, 2007, the three-month shortened statutory period for response to which expires on March 17, 2008. This response is submitted on or before two months from the mailing date of the Final Office Action, as February 17th was a Sunday and February 18th a Federal holiday.

A Listing of Claims (none being amended herein) begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.